





HSEC8-108-01-L-DP-A-K



HSEC8-DP SERIES

(0.80 mm) .0315"

IFFERENTIAL PAIR EDGE CARD SOCKET

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?HSEC8-DP

Insulator Material:

Black Liquid Crystal Polymer Contact: Copper Alloy Plating:
Au or Sn over
50 μ" (1.27 μm) Ni
Operating Temp:
Testing Now!
RoHS Compliant:

PROCESSING

Lead-Free Solderable:

SMT Lead Coplanarity: (0.10 mm) .004" max

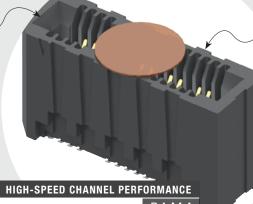
Card Mates:

(1.60 mm) .062" thick card

APPLICATION

Contacts

High-Speed Edge Rate®



DP

Designed for high-speed differential pair applications

HSEC8-DP

Rating based on Samtec reference channel. For full SI performance data visit Samtec.com or contact SIG@samtec.com

PLATING

OPTION

PAM4

Optional weld tab available

ALSO AVAILABLE

HSEC8

- · Other platings
- · Other pin counts

(MOQ Required)

08, 12, 16, 20, 32, 56 (Total Pairs)

NO. OF

PAIRS

(8.98) .353

= 10 μ" (0.25 μm) Gold on contact, Matte Tin on tail

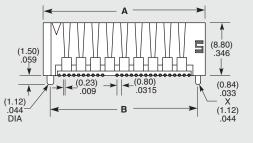
(5.60) .220

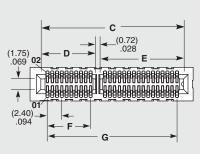
(Leave blank for no weld tab) -WT= Weld Tab

OPTION

–K = (6.25 mm) .246" DIA Polyimide Film Pick & Place Pad

K





HSEC8-16-01-L-DP-A SHOWN

NO. OF PAIRS	Α	В	С	D	Е	F	G
08	(17.40)	(15.00)	(14.20)	(4.34)	(9.14)	(2.40)	(12.00)
	.685	.591	.559	.171	.360	.094	.472
12	(22.20)	(19.80)	(19.00)	(6.74)	(11.54)	(4.80)	(16.80)
	.874	.780	.748	.265	.454	.189	.661
16	(27.00)	(24.60)	(23.80)	(9.14)	(13.94)	(7.20)	(21.60)
	1.063	.969	.937	.360	.549	.283	.850
20	(31.80)	(29.40)	(28.60)	(11.54)	(16.34)	(9.60)	(26.40)
	1.252	1.157	1.126	.454	.643	.378	1.039
32	(46.20)	(43.80)	(43.00)	(18.74)	(23.54)	(16.80)	(40.80)
	1.819	1.724	1.693	.738	.927	.661	1.606
56	(75.00)	(72.60)	(71.80)	(33.14)	(37.94)	(31.20)	(69.60)
	2.953	2.858	2.827	1.305	1.494	1.228	2.740

Note:

Some sizes, styles and options are nonstandard, non-returnable.

Due to technical progress, all designs, specifications and components are subject to change without notice